

Updated: 23.01.2025


WTF® D3 WOOD GLUE

Package size	250 ml, 750 ml
Color	white
Description	D3 Wood Glue is a ready to use, fast drying, PVA-based adhesive with superior water resistance (D3).

TECHNICAL INFORMATION

Basis	PVAc
Consistency	High viscous fluid
Curing system	Physical drying
Density	Ca. 1,10 g/ml
Viscosity (Brookfield)	8.000 mPa.s → 15.000 mPa.s
Total solid content	Ca. 50 %
Open time (+23°C, 55% RV)*	Ca. 8 min.
Pressing pressure	1 kg/cm ² → 2 kg/cm ²
Pressing times	See Use
Water resistance (EN204)	D3
Application temperature	+15 °C +35 °C
pH level	2,5 3,5
Min. Film Forming Temperature (MFFT)	+5 °C
Consumption*	80 - 140 g/m ² in full surface bonding. 160 - 180 g/m ² in assembly.
Suitable for	Indoor and outdoor use
Shelf-life	12 month
Storage	Unopened and stored in dry and cool conditions (Between +5 and +25 °C)

* These values may vary depending on environmental factors such as temperature, moisture, and type of substrates. ** This information relates to fully cured product.

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WORLD'S TOUGHEST FIX

WTF[®] D3 WOOD GLUE

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BENEFITS

- Easy to tool
- Transparent after drying
- High end strength
- Fast drying time
- Resistant against high temperatures

APPLICATIONS

- Interior applications with frequent short-term exposure of the bonds to running or condensed water.
- Interior applications which are exposed to high relative humidity.
- Exterior applications which are not exposed to weather factors.
- Manufacturing of door and window-frames that need to meet class D3 according to EN204.
- Bonding of wood, board, chipboard, veneer
- Assembly glueing of soft wood
- Construction bonding such as mortise and tenon joints, punches, etc.
- Stationary edge-banding with veneers, plastic laminates and solid wood strips
- Surface bonding of decor-finish film, HPL and CPL to chipboard, MDF and plywood.
- Bonding joints in boards and block bonding of softwood, hardwood and chipboard.

SURFACE PREPARATION

Substrates: Many non-porous and porous substrates like wood, carton, laminate, etc.

Nature: The to be bonded materials should be flat and well fitting as well as clean, dry and free of dust and grease.

Surface preparation: Slightly grinding smooth non-porous surfaces can improve the adhesion. We recommend a preliminary adhesion test on any substrate.

USE

- **Application method:** Apply the adhesive with a notched trowel, brush or machine on one of the materials to be bonded. Join the parts together and clamp for 1 to 2 hours.
- **Pressing times:** if applicable. Curing time depends strongly on the used kind of wood, temperature, amount of adhesive and the porosity of the materials to be bonded. Minimum pressing times High-frequency bonding with longitudinal heating > 15 sec. and Dekor-finish 5 – 10 sec. Minimum pressing times assembly bondings: 8 – 15 min. Minimum pressing times bonding joints and block bonding: 10 – 15 min. Surface bonding of HPL/CPL in short cycle presses at 70°C: to plywood approx. 90 sec. and to chipboard approx. 45 sec.
- **Cleaning:** Before curing, D3 Wood Glue can be removed with water from substrates and tools. Cured D3 Wood Glue can only be removed mechanically.
- **Repair:** With the same material.
- **Note:** When bonding certain woods such as beech and cherry discoloration may occur because of the variety of composition and pretreatment.
- **Note:** Do not dilute the adhesive.

For more information, see the safety data sheet



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2 / 2

TECHNICAL DATASHEET

TDS